

IN THE CLAIMS:

1-28 (Cancelled)

29. (New) A semiconductor device manufacturing method comprising the steps of:

converting into a plasma a process gas containing N_2O and a hydrocarbon C_xH_y ;

nitriding a surface portion of a copper wiring layer to convert the surface portion into a copper diffusion preventing layer by exposing a surface of the copper wiring layer to the process gas plasma.

30. (New) A semiconductor device manufacturing method according to claim 29, wherein N_2 is added to the process gas.

31. (New) A semiconductor device manufacturing method according to claim 29, further comprising the step of:

before converting the process gas into the plasma, exposing the surface of the copper wiring layer to a NH_3 plasma to remove surface oxide from the copper wiring layer.

32. (New) A semiconductor device manufacturing method according to claim 29, further comprising the step of:

after forming the copper diffusion preventing layer, forming a silicon-containing insulating layer on the copper wiring layer.

33. (New) A semiconductor device manufacturing method according to claim 32, further comprising the step of:

converting into a second plasma a process gas containing at least one of NH_3 , N_2 , and N_2O ; and

exposing the silicon-containing insulating layer to the second process gas plasma.

34. (New) A semiconductor device manufacturing method according to claim 32, further comprising the steps of:

forming an interlayer insulating film on the silicon-containing insulating film;

forming a via hole in the silicon-containing insulating film and the interlayer insulating film;

burying a plug, electrically connected to the copper wiring, in the via hole; and

forming an upper wiring layer, electrically connected to the plug, on the interlayer insulating film.

35. (New) A semiconductor device manufacturing method according to claim 34, wherein the interlayer insulating film is a FSG film or a porous SiO_2 film.

36. (New) A semiconductor device manufacturing method according to claim 32, wherein the silicon-containing insulating layer is selected from the group consisting of a SiOCH layer, a SiCH layer, a SiO layer, a SiN layer, a SiONCH layer, and a SiCNH layer.

37. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiOCH film formed by chemical vapor deposition using a reaction gas containing a compound having siloxane bonds.

38. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiONCH film formed by chemical vapor deposition using a reaction gas containing a compound having siloxane bonds and N_2O .

39. (New) A semiconductor device manufacturing method according to claim 38, wherein the compound having the siloxane bonds is selected from the group consisting of HMDSO $((Si(CH_3)_3)_2O)$, OMCTS $((Si(CH_3)_2)_4O_4)$, HEDS $((Si(C_2H_5)_3)_2O)$, TMDS $((SiH(CH_3)_2)_2O)$, TEDS $((SiH(C_2H_5)_2)_2O)$, TMCTS $((SiH(CH_3)_4)_4O_4)$, and TECTS $((SiH(C_2H_5)_4)_4O_4)$.

40. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiN film formed by chemical vapor deposition using a reaction gas containing SiH_4 and N_2O .

41. (New) A semiconductor device manufacturing method according to claim 40, wherein NH_3 is added to the reaction gas.

42. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiO film formed by chemical vapor deposition using a

reaction gas containing an organic silane.

43. (New) A semiconductor device manufacturing method according to claim 42, wherein the organic silane is TMS ($\text{Si}(\text{CH}_3)_4$).

44. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiCH film formed by chemical vapor deposition using a reaction gas containing organic silane and hydrocarbon.

45. (New) A semiconductor device manufacturing method according to claim 44, wherein the hydrocarbon is CH_4 or C_2H_2 .

46. (New) A semiconductor device manufacturing method according to claim 36, wherein the silicon-containing insulating layer is a SiCNH film formed by chemical vapor deposition using a reaction gas containing NH_3 , organic silane, and hydrocarbon.

47. (New) A semiconductor device manufacturing method according to claim 37, wherein the compound having the siloxane bonds is selected from the group consisting of HMDSO ($((\text{Si}(\text{CH}_3)_3)_2\text{O})$), OMCTS ($((\text{Si}(\text{CH}_3)_2)_4\text{O}_4)$), HEDS ($((\text{Si}(\text{C}_2\text{H}_5)_3)_2\text{O})$), TMDS ($((\text{SiH}(\text{CH}_3)_2)_2\text{O})$), TEDS ($((\text{SiH}(\text{C}_2\text{H}_5)_2)_2\text{O})$), TMCTS ($((\text{SiH}(\text{CH}_3))_4\text{O}_4)$), and TECTS ($((\text{SiH}(\text{C}_2\text{H}_5))_4\text{O}_4)$).